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(54) Title: **PROCESS FOR PROMOTING ADHESION BETWEEN AN INORGANIC SUBSTRATE AND AN ORGANIC POLYMER**

(57) Abstract: The invention relates to a process, and compositions for its implementation, to promote adhesion between an inorganic substrate and an organic polymer, especially between the copper surfaces of printed circuits for electronic use and a polymer resin, in which an organometallic layer of a dark brown colour, which is very uniform and compact, is deposited on the inorganic substrate by means of treatment in a composition which comprises: a) a silane or a mixture of functional organic silanes with a structure represented by the following general formula: $Y-(CH_2)_n-Si(OR)_3$ where: Y represents a functional organic group, n is a number which has a value between 0 and 3, and R represents a hydrogen atom or any easily hydrolysable group which is capable of releasing an atom of hydrogen; b) an azole compound; c) an oxygen carrier; d) an organic or inorganic acid; and preferably e) a zinc compound. The process and the composition according to the invention ensure a considerable increase in adhesion between the inorganic substrate and the organic polymer.

WO 00/74451 A1